

CONFERENCES IN 2008:

NOVEMBER:

2nd Int'l **Symposium on Photonic Packaging**
November 13, 2008; Munich, Germany
www.mcc-pr.de/phonics/site
Contact: phonics@mcc-pr.de

DECEMBER:

9th **VLSI Packaging Workshop in Japan**
December 1 - 2, 2008; Kyoto, Japan
vlsi-pkg-ws.org
Contact: Michitaka Kimura, Renesas Technology Corp,
kimura.michitaka@renesas.com

10th **Electronics Packaging Technology Conference** (EPTC 2008) www.eptc-ieee.net
December 9-12, 2008; Singapore
Contact: Dr. Tong Yan Tee, tytee@amkor.com

Electrical Design of Advanced Packaging and Systems (EDAPS 2008) www.edaps2008.org
December 10-12, 2008 COEX Conference Center
Seoul, Korea
Contact: S.M Yang, yangsm@ee.kaist.ac.kr (Office:
+82-42-869-5458)

2nd Int'l Conference on **Thermal issues in Emerging Technologies, Theory and Applications** (ThETA2)
December 17-20, 2008 Cairo, Egypt
www.thetaconf.org
Contact: thetaconf@gmail.com

CONFERENCES IN 2009:

JANUARY:

2009 **European Systems Packaging Workshop** (ESPW) www.semi-therm.org
February 2-4, 2009 Kinsale, Ireland
Contact: Alan Mathewson, alan.mathewson@tyndall.ie

FEBRUARY:

8th Annual **FLEXIBLE Electronics & Displays Conference & Exhibition** www.flextech.org
February 2-5, 2009 Phoenix, AZ, USA
Contact: Alan Mathewson, events@usdc.org

MARCH:

2009 **Semiconductor Thermal Measurement and Management Symposium** (SEMI-THERM 25)
www.semi-therm.org
March 15-19, 2009 San Jose, CA USA
Contact: Tom Tarter, ttarter@ieee.org

APRIL:

Design, Test, Integration and Packaging of MEMS/MOEMS (DTIP)
cmp.imag.fr/conferences/dtip/dtip2009
April 1-3, 2009 Rome, Italy
Contact: Chantal Benis-Morel, chantal.benis@imag.fr

International Conference on Electronics Packaging (ICEP) www.jiep.or.jp/icep
April 14-16 Kyoto, Japan

10th Int'l **Conference on Thermal, Mechanical and Multiphysics Simulation and Experiments in Micro-Electronics and Micro-Systems** (EuroSimE 2009)
www.eurosime.org
April 26-29 2009 Technical University of Delft, The Netherlands
Contact: eurosime@astefo.com

MAY:

Workshop on Signal Propagation on Interconnects (SPI'09) spi.univ-brest.fr
May 12-15, 2009 Hotel Sofitel, Strasbourg, France
Abstracts due: February 7, 2009
Contact: Denis Deschacht, denis.deschacht@lirmm.fr

59th **Electronic Components and Technology Conference** (ECTC 2009) www.ectc.net
May 25-29, 2009 San Diego, CA USA
Contact: Jean Trehwella, jeanmh@us.ibm.com

JUNE:

European Microelectronics and Packaging Conference & Exhibition (EMPC 2009)
www.empc2009.org
June 14-17, 2009 Rimini, Italy
Abstracts due: December 31, 2008
Contact: Pragma Congressi, segreteria@empc2009.org

IEEE International Workshop on **Advances in Sensors and Interfaces** (IWASI'09) iwasi.poliba.it
June 25-26, 2009 Trani, Italy
Papers due: February 28, 2009
Contact: Prof. Daniela De Venuto, d.devenuto@poliba.it

SEPTEMBER:

2009 **IEEE Holm Conference on Electrical Contacts (Holm 2009)**
www.ewh.ieee.org/soc/cpmt/tc1/h2009/h2009top.html
Sept. 14-16, 2009 Vancouver, BC, Canada
Papers due: January 9, 2009
Contact: April Coles, a.coles@ieee.org

See the CPMT Society website for updates:

www.cpmt.org/conf